

AMENDMENTS TO THE CLAIMS

Please amend the claims as follows.

1. (Currently Amended) A mounting structure of a ball grid array type IC comprising:
resin guide ribs provided on opposite sides of a body portion of the ball grid array type IC;
engaging pawls formed at distal ends of the guide ribs so as to be locked into locking holes of a board;
springs in which the guide ribs are inserted respectively; and
height adjusting ribs provided at places slightly inwardly distant from the guide ribs respectively so as to protrude from the body portion;
wherein the springs prevent the ball grid array type IC from being strongly pressed against the board when the ball grid array type IC is mounted on the board; and
wherein the height adjusting ribs adjust the ball grid array type IC to a predetermined height relative to the board.
2. (Currently Amended) A mounting structure of a ball grid array type IC comprising:
resin guide ribs provided on opposite sides of a body portion of the ball grid array type IC;
engaging pawls formed at distal ends of the guide ribs so as to be locked into locking holes of a board; and
elastic bodies provided on the guide ribs;
wherein the elastic bodies prevent the ball grid array type IC from being strongly pressed against the board when the ball grid array type IC is mounted on the board.
3. (Original) The mounting structure of a ball grid array type IC according to claim 2, further comprising height adjusting ribs integrally formed on sides of the guide ribs respectively.
4. (Original) The mounting structure of a ball grid array type IC according to claim 2, wherein the elastic bodies are made of elastic pieces provided on sides of the guide ribs so as to be integrated with the guide ribs respectively and extend toward the board.

5. (Currently Amended) A mounting structure of a ball grid array type IC comprising:
 - a plurality of solder balls provided on a bottom surface of a body portion of the ball grid array type IC for mounting the ball grid array type IC on a board;
 - wherein a pair of anti-rubbing pins to be fitted into insertion holes provided in the board are provided on diagonal corners of the bottom surface of the body portion respectively so as to protrude downward.
6. (Currently Amended) A mounting structure of a ball grid array type IC comprising:
 - a plurality of solder balls provided on a bottom surface of a body portion of the ball grid array type IC for mounting the ball grid array type IC on a board;
 - wherein at least one anti-rubbing pin to be fitted in an insertion hole provided in the board is provided on the bottom surface of the body portion so as to protrude downward.
7. (Original) The mounting structure of a ball grid array type IC according to claim 6, wherein the anti-rubbing pin is provided on each of three corners of the body portion so as to protrude downward.
8. (Currently Amended) The mounting structure of a ball grid array type IC according to claim 6,
 - wherein the anti-rubbing pin is provided on one corner of the body portion so as to protrude downward; and
 - wherein a pin which is shaped like a square in section and which serves as an orienting pin and also as a positioning pin to be inserted into a square hole formed in the board is provided on another corner of the bottom surface of the body portion diagonally opposite the anti-rubbing pin, so as to protrude downward.